

HiPerFRED

$$V_{RRM} = 1200 \text{ V}$$

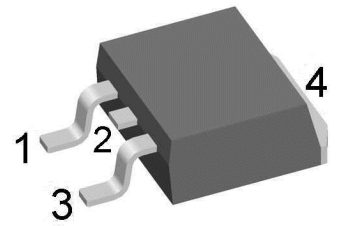
$$I_{FAV} = 2 \times 8 \text{ A}$$

$$t_{rr} = 40 \text{ ns}$$

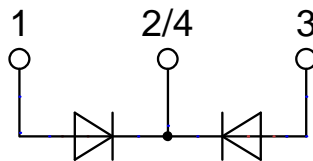
High Performance Fast Recovery Diode
Low Loss and Soft Recovery
Common Cathode

Part number

DSEC16-12AS



Backside: cathode



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low I_{rm} -values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low I_{rm} reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: TO-263 (D2Pak)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

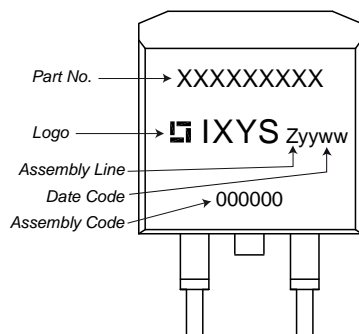
- to perform joint risk and quality assessments;

- the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

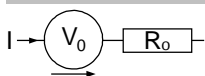
Fast Diode				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
V_{RSM}	max. non-repetitive reverse blocking voltage				1200	V	
V_{RRM}	max. repetitive reverse blocking voltage				1200	V	
I_R	reverse current, drain current	$V_R = 1200\text{ V}$			60	μA	
		$V_R = 1200\text{ V}$			0.25	mA	
V_F	forward voltage drop	$I_F = 10\text{ A}$			2.94	V	
		$I_F = 20\text{ A}$			3.57	V	
		$I_F = 10\text{ A}$			1.96	V	
		$I_F = 20\text{ A}$			2.56	V	
I_{FAV}	average forward current	$T_C = 135^\circ\text{C}$			8	A	
		rectangular $d = 0.5$					
V_{FO}	threshold voltage	} for power loss calculation only			1.20	V	
r_F	slope resistance				57	m Ω	
R_{thJC}	thermal resistance junction to case				2.5	K/W	
R_{thCH}	thermal resistance case to heatsink			0.25		K/W	
P_{tot}	total power dissipation				60	W	
I_{FSM}	max. forward surge current	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}; V_R = 0\text{ V}$			40	A	
C_J	junction capacitance	$V_R = 600\text{ V}$ $f = 1\text{ MHz}$			3	pF	
I_{RM}	max. reverse recovery current	} $I_F = 10\text{ A}; V_R = 800\text{ V}$ $-di_F/dt = 200\text{ A}/\mu\text{s}$			4	A	
					8	A	
t_{rr}	reverse recovery time		$T_{VJ} = 25^\circ\text{C}$			40	ns
			$T_{VJ} = 125^\circ\text{C}$			115	ns

Package TO-263 (D2Pak)			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			35	A
T_{VJ}	virtual junction temperature		-55		175	°C
T_{op}	operation temperature		-55		150	°C
T_{stg}	storage temperature		-55		150	°C
Weight				2		g
F_C	mounting force with clip		20		60	N

Product Marking


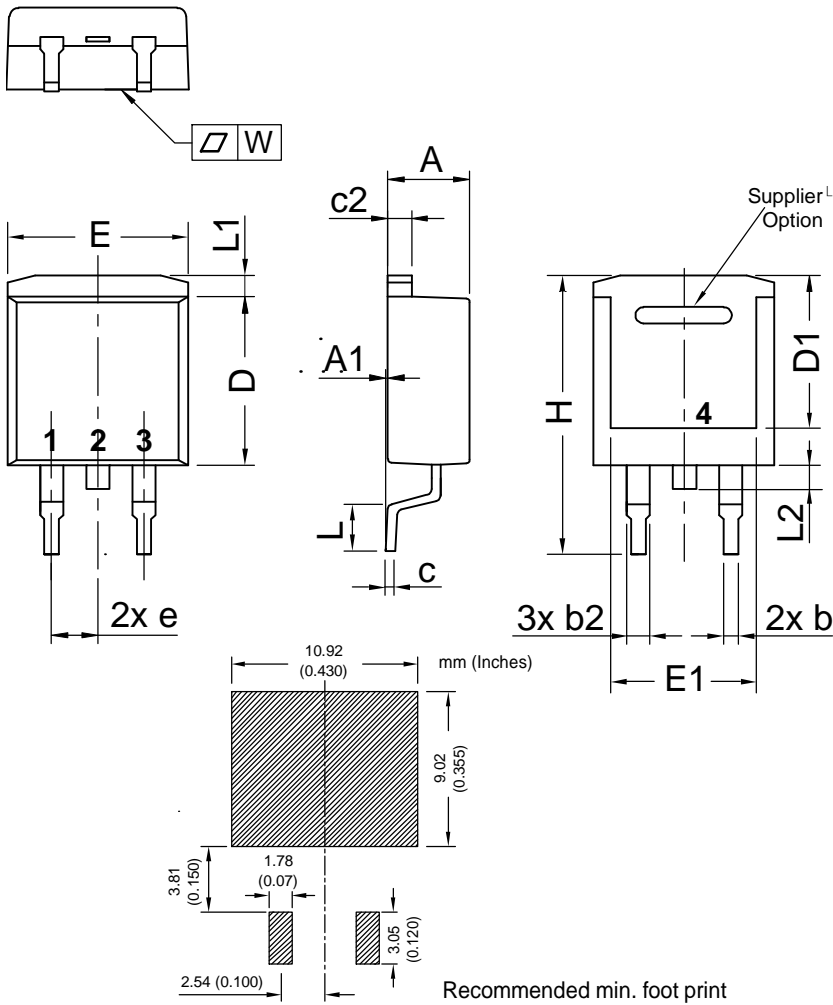
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEC16-12AS	DSEC16-12AS	Tape & Reel	800	507922
Alternative	DSEC16-12AS-TUB	DSEC16-12AS	Tube	50	507915

Similar Part	Package	Voltage class
DSEC16-12A	TO-220AB (3)	1200

Equivalent Circuits for Simulation
** on die level*
 $T_{VJ} = 175\text{ °C}$

Fast Diode

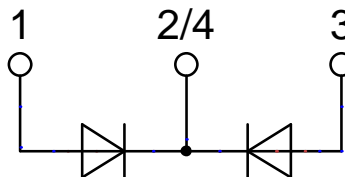
$V_{0\ max}$	threshold voltage	1.2	V
$R_{0\ max}$	slope resistance *	54	mΩ

Outlines TO-263 (D2Pak)



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.06	4.83	0.160	0.190
A1	typ. 0.10		typ. 0.004	
A2	2.41		0.095	
b	0.51	0.99	0.020	0.039
b2	1.14	1.40	0.045	0.055
c	0.40	0.74	0.016	0.029
c2	1.14	1.40	0.045	0.055
D	8.38	9.40	0.330	0.370
D1	8.00	8.89	0.315	0.350
D2	2.5		0.098	
E	9.65	10.41	0.380	0.410
E1	6.22	8.50	0.245	0.335
e	2,54 BSC		0,100 BSC	
e1	4.28		0.169	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	1.02	1.68	0.040	0.066
W	typ. 0.02	0.040	typ. 0.0008	0.002

All dimensions conform with and/or within JEDEC standard.



Fast Diode

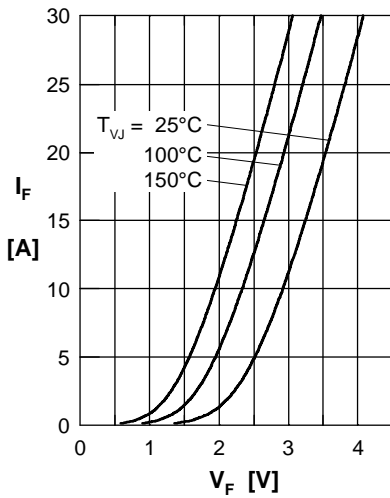


Fig. 1 Forward current I_F versus V_F

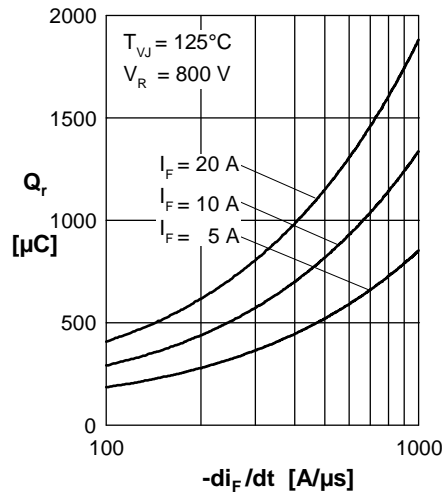


Fig. 2 Typ. reverse recov. charge Q_r versus $-di_F/dt$

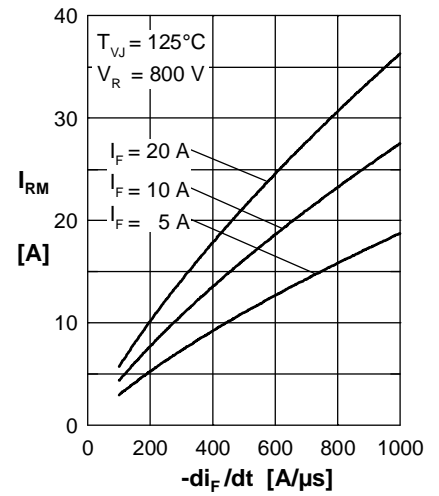


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

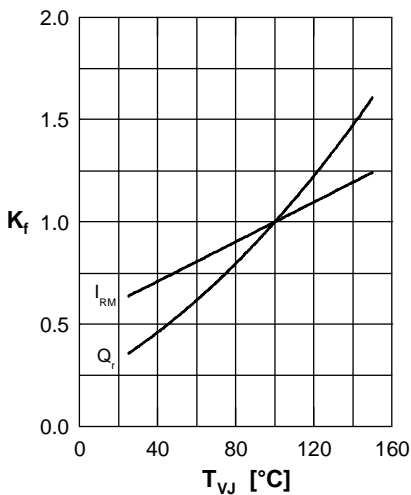


Fig. 4 Typ. dynamic parameters Q_r , I_{RM} versus T_{VJ}

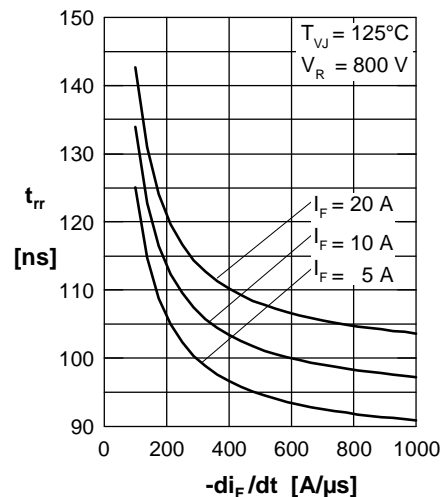


Fig. 5 Typ. recovery time t_{rr} versus $-di_F/dt$

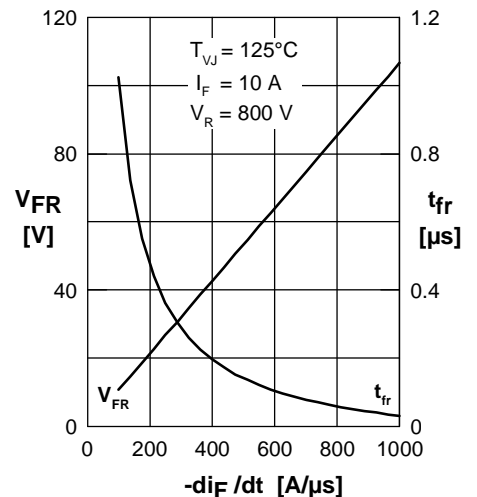


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt

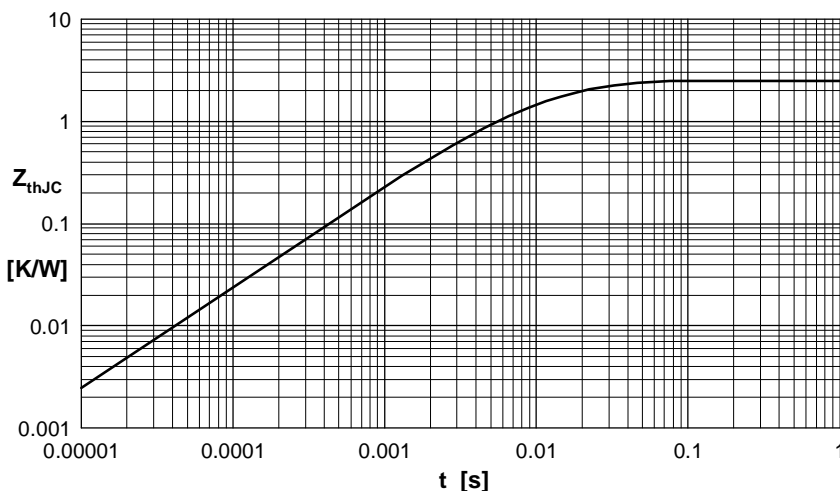


Fig. 7 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0200	0.0002
2	0.3000	0.0040
3	0.8000	0.0200
4	1.3800	0.0100